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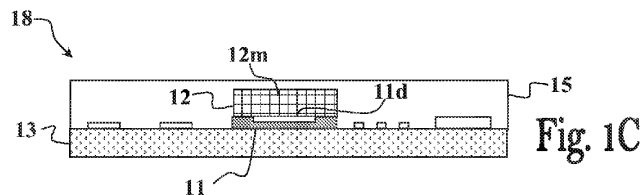
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(54) **Title:** ENCAPSULATION TECHNIQUES



(57) **Abstract:** An integrated circuit (IC) assembly and a method for encapsulating of IC are presented. The IC assembly comprises an IC substrate having one or more micro-devices, at least one dielectric matrix element placed on said IC substrate over at least one of its one or more micro-devices; and an encapsulation element applied over said IC substrate and said at least one dielectric matrix element placed thereon to enclose and seal said IC substrate.



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